



## Material Content Data Sheet



<b>Sales Product Name</b>		BTS50015-1TAD		<b>Issued</b>		1. August 2018		
<b>MA#</b>		MA001381572						
<b>Package</b>		PG-TO263-7-8		<b>Weight*</b>		1522.88 mg		
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]
chip	inorganic material	silicon	7440-21-3	13.102	0.86	0.86	8603	8603
leadframe	non noble metal	iron	7439-89-6	0.798	0.05		524	
	inorganic material	phosphorus	7723-14-0	0.239	0.02		157	
	non noble metal	copper	7440-50-8	797.119	52.34	52.41	523427	524108
wire	non noble metal	aluminium	7429-90-5	11.066	0.73	0.73	7267	7267
encapsulation	organic material	carbon black	1333-86-4	8.622	0.57		5662	
	plastics	epoxy resin	-	94.846	6.23		62281	
	inorganic material	silicondioxide	60676-86-0	471.357	30.95	37.75	309516	377459
leadfinish	non noble metal	tin	7440-31-5	8.717	0.57	0.57	5724	5724
plating	inorganic material	phosphorus	7723-14-0	0.008	0.00		5	
	non noble metal	nickel	7440-02-0	3.244	0.21	0.21	2130	2135
glue	plastics	Polyimide	26023-21-2	0.198	0.01	0.01	130	130
solder	noble metal	silver	7440-22-4	0.180	0.01		118	
	non noble metal	tin	7440-31-5	0.144	0.01		95	
	non noble metal	lead	7439-92-1	6.878	0.45	0.47	4516	4729
heatspreader	non noble metal	iron	7439-89-6	0.106	0.01		70	
	inorganic material	phosphorus	7723-14-0	0.032	0.00		21	
	non noble metal	copper	7440-50-8	106.227	6.98	6.99	69754	69845
*deviation	< 10%				Sum in total:	100.00		1000000

### Important Remarks:

1. Infineon Technologies AG provides full material declaration based on information provided by third parties and has taken and continues to take reasonable steps to provide representative and accurate information.
2. Infineon Technologies AG and Infineon Technologies AG suppliers consider certain information to be proprietary, and thus CAS numbers and other limited information may not be available for release.
3. All statements are based on our present knowledge, are provided 'as is' and may be subject to change at any time due to technical requirements and development without notification.

This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and contains Pb according RoHS exemption 7a, Lead in high melting temperature type solders.

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